

## 2.5-V 460-kbps RS-232 TRANSCEIVER WITH $\pm 15$ -kV ESD PROTECTION

Check for Samples: [MAX3318](#)

### FEATURES

- ESD Protection for RS-232 I/O Pins
  - $\pm 15$  kV (Human-Body Model)
  - $\pm 8$  kV (IEC 61000-4-2, Contact Discharge)
  - $\pm 8$  kV (IEC 61000-4-2, Air-Gap Discharge)
- 300- $\mu$ A Operating Supply Current
- 1- $\mu$ A Low-Power Standby (With Receivers Active) Mode
- Designed to Transmit at a Data Rate of 460 kbps
- Auto-Power-Down Plus Option Features Flexible Power-Saving Mode
- Operates From a Single 2.25-V to 3-V  $V_{CC}$  Supply

### APPLICATIONS

- Battery-Powered Systems
- PDAs
- Cellular Phones
- Notebooks
- Hand-Held Equipment
- Pagers

### DESCRIPTION

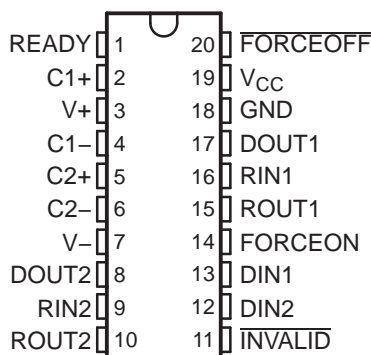
The MAX3318 is a dual-driver, dual-receiver, RS-232 compatible transceiver. The device features auto-power-down plus and enhanced electrostatic discharge (ESD) protection integrated into the chip. Driver output and receiver input are protected to  $\pm 8$  kV using the IEC 61000-4-2 Air-Gap Discharge method,  $\pm 8$  kV using the IEC 61000-4-2 Contact Discharge method, and  $\pm 15$  kV using the Human-Body Model (HBM).

The device operates at a data rate of 460 kbps. The transceiver has a proprietary low-dropout driver output stage enabling RS-232-compatible operation from a 2.25-V to 3-V supply with a dual charge pump. The charge pump requires only four 0.1- $\mu$ F capacitors and features a logic-level output (READY) that asserts when the charge pump is regulating and the device is ready to begin transmitting.

The MAX3318 achieves a 1- $\mu$ A supply current using the auto-power-down feature. This device automatically enters a low-power power-down mode when the RS-232 cable is disconnected or the drivers of the connected peripherals are inactive for more than 30 s. The device turns on again when it senses a valid transition at any driver or receiver input. Auto power down saves power without changes to the existing BIOS or operating system.

This device is available in two space-saving packages: 20-pin SSOP and 20-pin TSSOP.

DB OR PW PACKAGE  
(TOP VIEW)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

## DETAILED DESCRIPTION

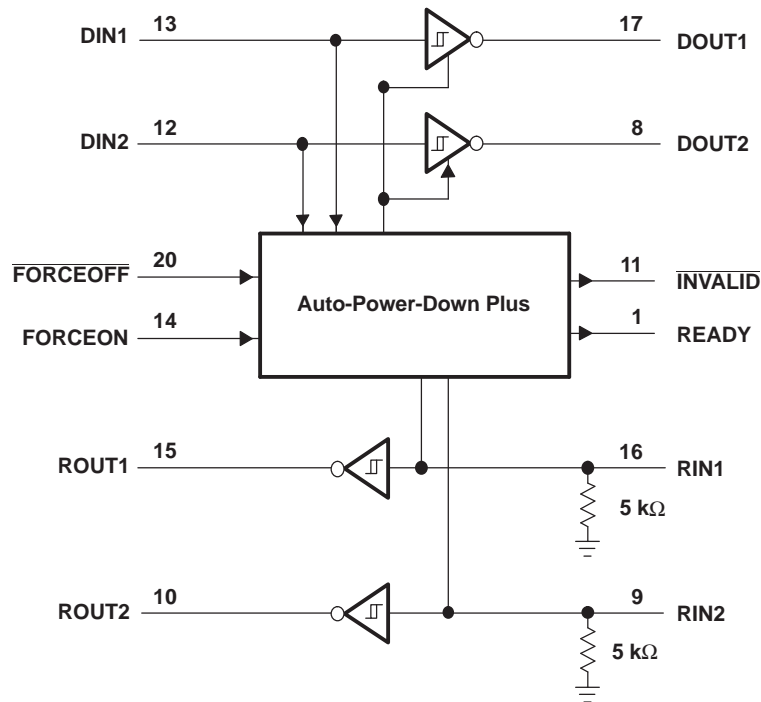
Flexible control options for power management are featured when the serial port and driver inputs are inactive. The auto-power-down plus feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the device does not sense valid signal transitions on all receiver and driver inputs for approximately 30 s, the built-in charge pump and drivers are powered down, reducing the supply current to 1  $\mu$ A. By disconnecting the serial port or placing the peripheral drivers off, auto-power-down plus can be disabled when FORCEON and FORCEOFF are high. With auto-power-down plus enabled, the device activates automatically when a valid signal is applied to any receiver or driver input. INVALID is high (valid data) if any receiver input voltage is greater than 2.7 V or less than –2.7 V, or has been between –0.3 V and 0.3 V for less than 30  $\mu$ s (typical number). INVALID is low (invalid data) if all receiver input voltage are between –0.3 V and 0.3 V for more than 30  $\mu$ s (typical number).

**FUNCTION TABLE<sup>(1)</sup>**

INPUT CONDITIONS				OUTPUT STATES				OPERATING MODE
FORCEON	<u>FORCEOFF</u>	RECEIVER OR DRIVER EDGE WITHIN 30 s	VALID RS-232 LEVEL PRESENT AT RECEIVER	DRIVER	RECEIVER	<u>INVALID</u>	READY	
Auto-Power-Down Plus Conditions								
H	H	No	No	Active	Active	L	H	Normal operation, auto-power-down plus disabled
H	H	No	Yes	Active	Active	H	H	Normal operation, auto-power-down plus disabled
L	H	Yes	No	Active	Active	L	H	Normal operation, auto-power-down plus enabled
L	H	Yes	Yes	Active	Active	H	H	Normal operation, auto-power-down plus enabled
L	H	No	No	Z	Active	L	L	Power down, auto-power-down plus enabled
L	H	No	Yes	Z	Active	H	L	Power down, auto-power-down plus enabled
X	L	X	No	Z	Active	L	L	Manual power down
X	L	X	Yes	Z	Active	H	L	Manual power down
Auto-Power-Down Conditions								
<u>INVALID</u>	<u>INVALID</u>	X	No	Z	Active	L	L	Power down, auto power down enabled
<u>INVALID</u>	<u>INVALID</u>	X	Yes	Active	Active	H	H	Normal operation, auto power down enabled

(1) H = high level, L = low level, X = irrelevant, Z = high impedance

### LOGIC DIAGRAM (POSITIVE LOGIC)



### TERMINAL FUNCTIONS

TERMINAL		DESCRIPTION
NAME	NO.	
C1+	2	Positive voltage-doubler charge-pump capacitor
C1–	4	Negative voltage-doubler charge-pump capacitor
C2+	5	Positive inverting charge-pump capacitor
C2–	6	Negative inverting charge-pump capacitor
DIN	12, 13	CMOS driver inputs
DOUT	8, 17	RS-232 driver outputs
$\overline{\text{FORCEOFF}}$	20	Force-off input, active low. Drive low to power down transmitters and charge pump. This overrides auto power down and FORCEON (see Function Table).
FORCEON	14	Force-on input, active high. Drive high to override auto power down, keeping transmitters on ( $\overline{\text{FORCEOFF}}$ must be high) (see Function Table).
GND	18	Ground
$\overline{\text{INVALID}}$	11	Valid signal detector output, active low. A logic high indicates that a valid RS-232 level is present on a receiver input.
READY	1	Ready to transmit output, active high. READY is enabled high when V– goes below –3.5 V and the device is ready to transmit.
RIN	9, 16	RS-232 receiver inputs
ROUT	10, 15	CMOS receiver outputs
V+	3	$2 \times V_{CC}$ generated by the charge pump
V–	7	$-2 \times V_{CC}$ generated by the charge pump
V <sub>CC</sub>	19	2.25-V to 3-V single-supply voltage

## Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$ to GND		–0.3	6	V
$V_+$ to GND <sup>(2)</sup>		–0.3	7	V
$V_-$ to GND <sup>(2)</sup>		–7	0.3	V
$V_+ +  V_- $ <sup>(2)</sup>			13	V
Input voltage	DIN, FORCEON, $\overline{\text{FORCEOFF}}$ to GND	–0.3	6	V
	RIN to GND		±25	
Output voltage	DOUT to GND		±13.2	V
	ROUT, $\overline{\text{INVALID}}$ , READY to GND	–0.3	$V_{CC} + 0.3$	
Short-circuit duration	DOUT to GND		Continuous	
Continuous power dissipation ( $T_A = 70^\circ\text{C}$ )	16-pin SSOP (derate 7.14 mW/ $^\circ\text{C}$ above $70^\circ\text{C}$ )		571	mW
	20-pin SSOP (derate 8 mW/ $^\circ\text{C}$ above $70^\circ\text{C}$ )		640	
	20-pin TSSOP (derate 7 mW/ $^\circ\text{C}$ above $70^\circ\text{C}$ )		559	
Storage temperature range		–65	150	$^\circ\text{C}$
Lead temperature (soldering, 10 s)			300	$^\circ\text{C}$

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2)  $V_+$  and  $V_-$  can have maximum magnitudes of 7 V, but their absolute difference cannot exceed 13 V.

## Recommended Operating Conditions

See Figure 4

				MIN	NOM	MAX	UNIT
Supply voltage				2.25	2.5	3	V
V <sub>IH</sub>	Driver and control high-level input voltage	DIN, $\overline{\text{FORCEOFF}}$ , FORCEON	V <sub>CC</sub> = 2.5 V to 3 V	0.7 × V <sub>CC</sub>		5.5	V
V <sub>IL</sub>	Driver and control low-level input voltage	DIN, $\overline{\text{FORCEOFF}}$ , FORCEON	V <sub>CC</sub> = 2.5 V to 3 V	0		0.3 × V <sub>CC</sub>	V
V <sub>I</sub>	Receiver input voltage			−25		25	V
T <sub>A</sub>	Operating free-air temperature	MAX3318C		0		70	°C
		MAX3318I		−40		85	

## Supply Current Section Electrical Characteristics

$V_{CC} = 2.25\text{ V}$  to  $3\text{ V}$ ,  $C1-C4 = 0.1\text{ }\mu\text{F}$ ,  $T_A = T_{MIN}$  to  $T_{MAX}$  (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	UNIT
<b>DC Characteristics (<math>V_{CC} = 2.5\text{ V}</math>, <math>T_A = 25^\circ\text{C}</math>)</b>					
Auto-power-down plus supply current	FORCEON = GND, $\overline{\text{FORCEOFF}} = V_{CC}$ , All RIN and DIN idle		1	10	$\mu\text{A}$
Auto-power-down supply current	$\overline{\text{FORCEOFF}} = \text{GND}$		1	10	$\mu\text{A}$
Supply current	FORCEON = $\overline{\text{FORCEOFF}} = V_{CC}$ , No load		0.3	2	mA

(1) Typical values are at  $V_{CC} = 2.5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

## ESD Protection

PARAMETER	TEST CONDITIONS	TYP	UNIT
RIN, DOUT	Human-Body Model (HBM)	$\pm 15$	kV
	IEC 61000-4-2 Air-Gap Discharge method	$\pm 8$	
	IEC 61000-4-2 Contact Discharge method	$\pm 8$	

## Driver Section Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature,

$V_{CC} = 2.25\text{ V}$  to  $3\text{ V}$ ,  $C1-C4 = 0.1\text{ }\mu\text{F}$ ,  $T_A = T_{MIN}$  to  $T_{MAX}$  (unless otherwise noted) (see [Figure 4](#))

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	UNIT
Driver input hysteresis			0.3		V
Input leakage current	FORCEON, DIN, $\overline{\text{FORCEOFF}}$		$\pm 0.01$	$\pm 1$	$\mu\text{A}$
Output voltage swing	All driver outputs loaded with $3\text{ k}\Omega$ to ground	$\pm 3.7$	$\pm 4$		V
Output resistance	$V_{CC} = 0$ , Driver output = $\pm 2\text{ V}$	300	10M		$\Omega$
Output short-circuit current <sup>(2)</sup>			$\pm 25$	$\pm 60$	mA
Output leakage current	$V_{CC} = 0$ or $2.25\text{ V}$ to $3\text{ V}$ , $V_{OUT} = \pm 12\text{ V}$ , Drivers disabled			$\pm 25$	$\mu\text{A}$

(1) Typical values are at  $V_{CC} = 2.5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

(2) Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

## Driver Section Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature,

$V_{CC} = 2.25\text{ V}$  to  $3\text{ V}$ ,  $C1-C4 = 0.1\text{ }\mu\text{F}$ ,  $T_A = T_{MIN}$  to  $T_{MAX}$  (unless otherwise noted) (see [Figure 1](#))

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	UNIT
Maximum data rate	$R_L = 3\text{ k}\Omega$ , $C_L = 1000\text{ pF}$ , One transmitter switching	460			kbps
$ t_{PHL} - t_{PLH} $ Driver skew <sup>(2)</sup>			100		ns
Transition-region slew rate	$V_{CC} = 2.5\text{ V}$ , $T_A = 25^\circ\text{C}$ , $R_L = 3\text{ k}\Omega$ to $7\text{ k}\Omega$ , Measured from $3\text{ V}$ to $-3\text{ V}$ or $-3\text{ V}$ to $3\text{ V}$ , $C_L = 150\text{ pF}$ to $2500\text{ pF}$	4		30	V/ $\mu\text{s}$

(1) Typical values are at  $V_{CC} = 2.5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

(2) Pulse skew is defined as  $|t_{PLH} - t_{PHL}|$  of each channel of the same device.

## Receiver Section Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature,  
 $V_{CC} = 2.25\text{ V to }3\text{ V}$ ,  $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$ ,  $T_A = T_{MIN}$  to  $T_{MAX}$  (unless otherwise noted) (see [Figure 4](#))

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	UNIT
Input voltage range		–25		25	V
Input threshold low	$T_A = 25^\circ\text{C}$			$0.3 \times V_{CC}$	V
Input threshold high	$T_A = 25^\circ\text{C}$	$0.7 \times V_{CC}$			V
Input hysteresis			0.3		V
Input resistance	$T_A = 25^\circ\text{C}$	3	5	7	k $\Omega$
Output leakage current		$\pm 0.05$		$\pm 10$	$\mu\text{A}$
Output voltage low	$I_{OUT} = 0.5\text{ mA}$			$0.1 \times V_{CC}$	V
Output voltage high	$I_{OUT} = -0.5\text{ mA}$	$0.9 \times V_{CC}$			V

(1) Typical values are at  $V_{CC} = 2.5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

## Receiver Section Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature,  
 $V_{CC} = 2.25\text{ V to }3\text{ V}$ ,  $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$ ,  $T_A = T_{MIN}$  to  $T_{MAX}$  (unless otherwise noted) (see [Figure 4](#))

PARAMETER	TEST CONDITIONS	TYP <sup>(1)</sup>	UNIT
$t_{PHL}$	Receiver propagation delay RIN to ROUT, $C_L = 150\text{ pF}$	0.175	$\mu\text{s}$
$t_{PLH}$		0.175	
$ t_{PHL} - t_{PLH} $	Receiver skew <sup>(2)</sup>	50	ns

(1) Typical values are at  $V_{CC} = 2.5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

(2) Pulse skew is defined as  $|t_{PLH} - t_{PHL}|$  of each channel of the same device.

## Auto-Power-Down Plus Section Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature,  
 $V_{CC} = 2.25\text{ V to }3\text{ V}$ ,  $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$ ,  $T_A = T_{MIN}$  to  $T_{MAX}$  (unless otherwise noted) (see [Figure 4](#))

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
Receiver input threshold to $\overline{\text{INVALID}}$ high	Positive threshold		2.7	V
	Negative threshold	–2.7		
Receiver input threshold $\overline{\text{INVALID}}$ low		–0.3	0.3	V
$\overline{\text{INVALID}}$ , READY voltage low	$I_{OUT} = 0.5\text{ mA}$		$0.1 \times V_{CC}$	V
$\overline{\text{INVALID}}$ , READY voltage high	$I_{OUT} = -0.5\text{ mA}$	$0.8 \times V_{CC}$		V

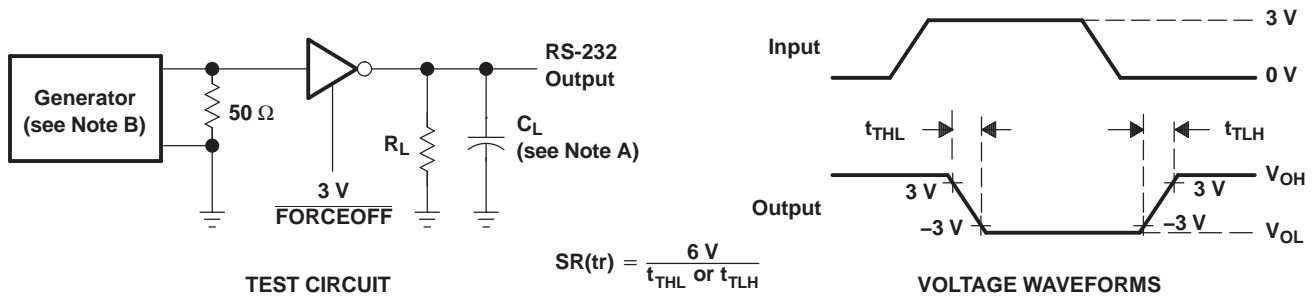
## Auto-Power-Down Plus Section Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature,  
 $V_{CC} = 2.25\text{ V to }3\text{ V}$ ,  $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$ ,  $T_A = T_{MIN}$  to  $T_{MAX}$  (unless otherwise noted) (see [Figure 4](#))

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	UNIT
$t_{INVH}$	Receiver positive or negative threshold to $\overline{\text{INVALID}}$ high $V_{CC} = 2.5\text{ V}$		1		$\mu\text{s}$
$t_{INVL}$	Receiver positive or negative threshold to $\overline{\text{INVALID}}$ low $V_{CC} = 2.5\text{ V}$		30		$\mu\text{s}$
$t_{WU}$	Receiver or driver edge to driver enabled $V_{CC} = 2.5\text{ V}$		100		$\mu\text{s}$
$t_{AUTOPRDN}$	Receiver or driver edge to driver shutdown $V_{CC} = 2.5\text{ V}$	15	30	60	s

(1) Typical values are at  $V_{CC} = 2.5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

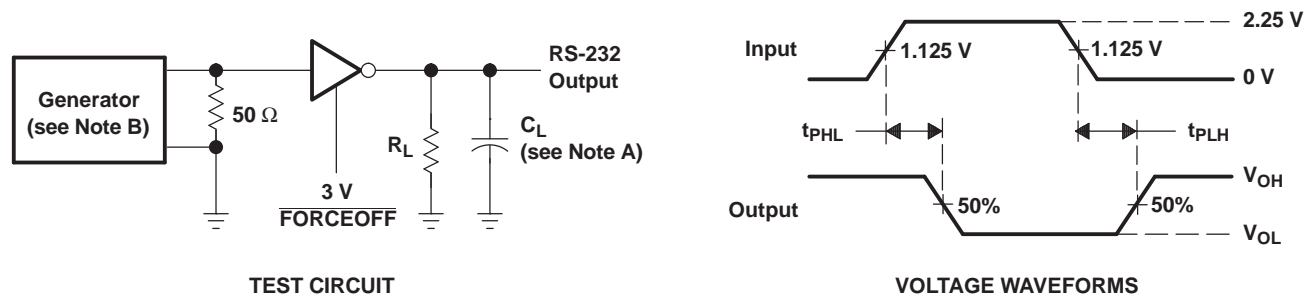
## PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10$  ns,  $t_f \leq 10$  ns.

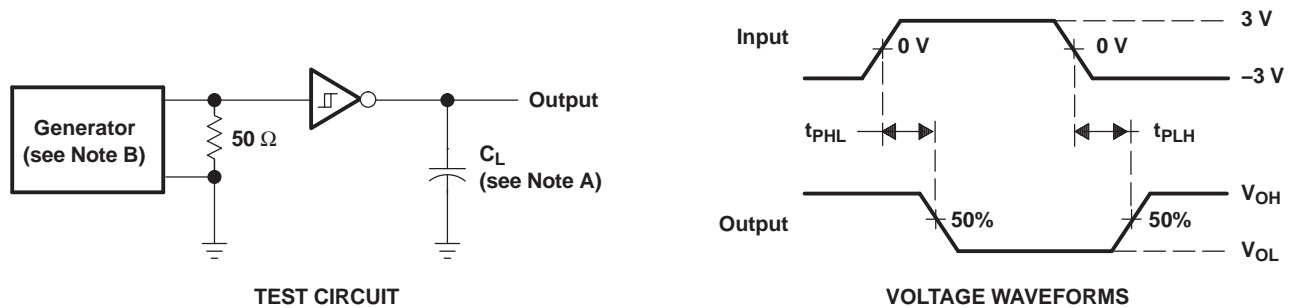
Figure 1. Driver Slew Rate



NOTES: A.  $C_L$  includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10$  ns,  $t_f \leq 10$  ns.

Figure 2. Driver Pulse Skew

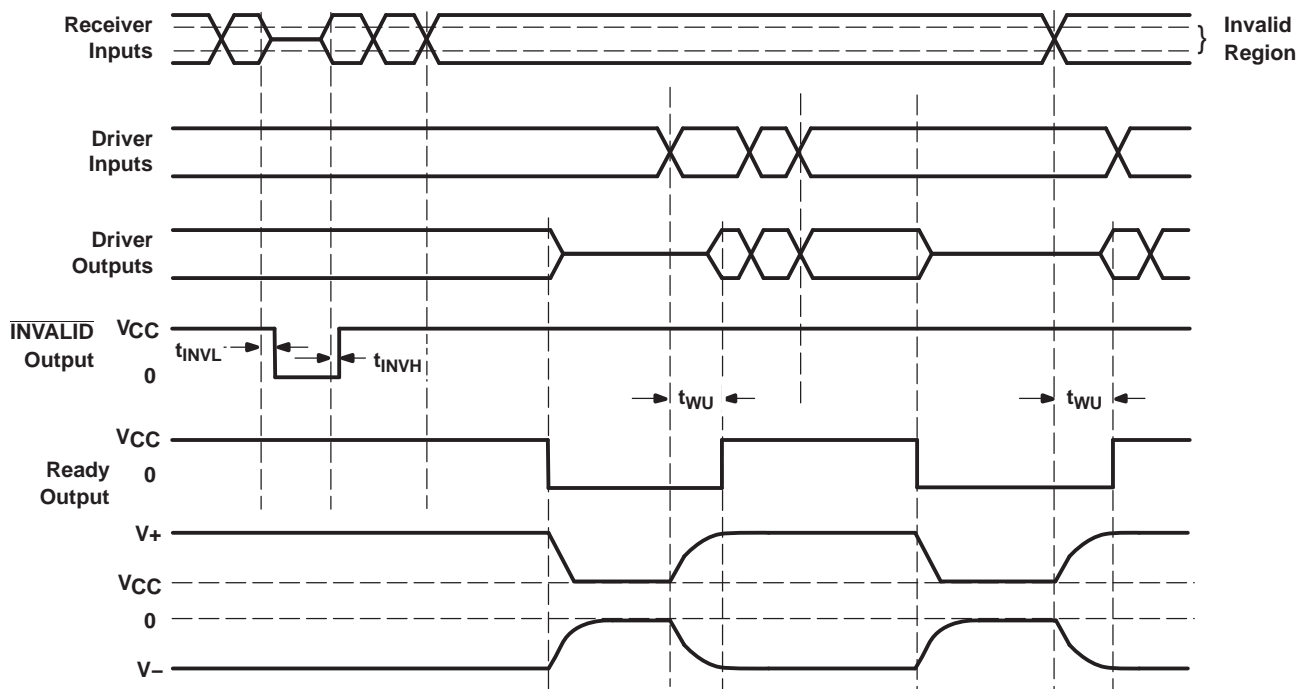


NOTES: A.  $C_L$  includes probe and jig capacitance.

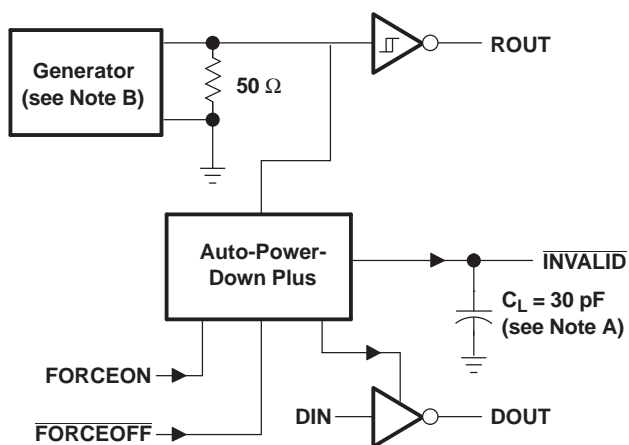
B. The pulse generator has the following characteristics:  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10$  ns,  $t_f \leq 10$  ns.

Figure 3. Receiver Propagation Delay Times

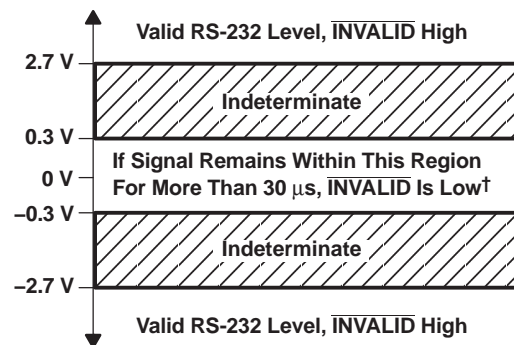
## PARAMETER MEASUREMENT INFORMATION



VOLTAGE WAVEFORMS



TEST CIRCUIT

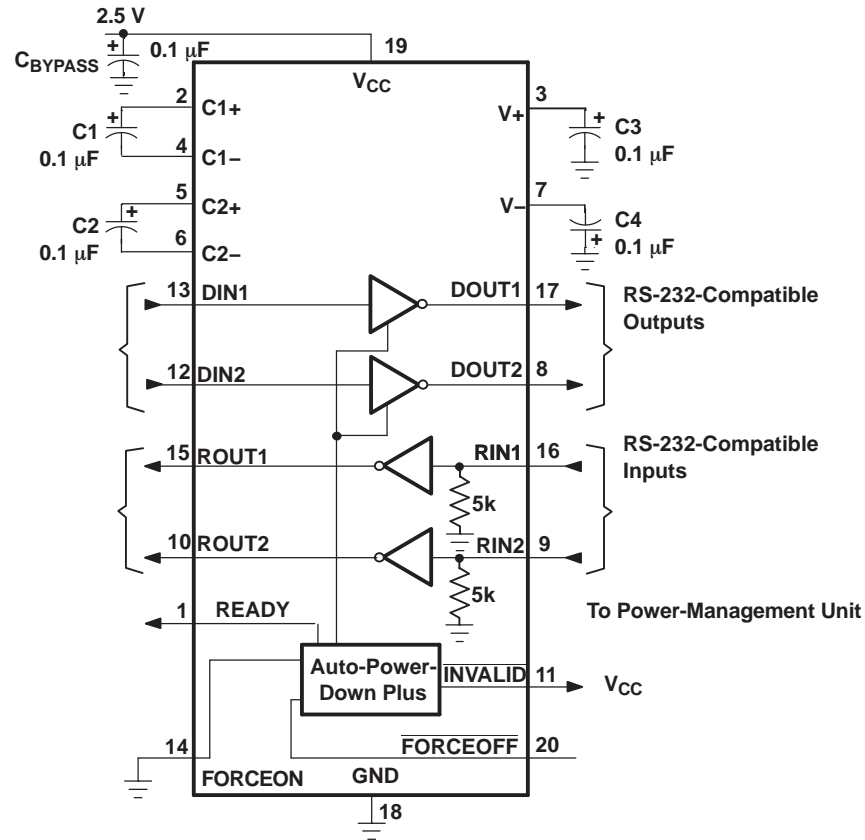


<sup>†</sup> Auto power down disables drivers and reduces supply current to 1  $\mu\text{A}$ .

Figure 4. **INVALID** Propagation Delay Times and Supply Enabling Time



## PARAMETER MEASUREMENT INFORMATION



**Figure 5. Typical Application Circuit**

## REVISION HISTORY

Changes from Original (June 2006) to Revision A	Page
• Updated document to new TI datasheet format - no specification changes. ....	<a href="#">1</a>
• Removed Ordering Information Table. ....	<a href="#">2</a>
• Updated TERMINAL FUNCTIONS table to fix inconsistency. ....	<a href="#">3</a>

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
MAX3318CDB	ACTIVE	SSOP	DB	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MP318C	<a href="#">Samples</a>
MAX3318CDBG4	ACTIVE	SSOP	DB	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MP318C	<a href="#">Samples</a>
MAX3318CDBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MP318C	<a href="#">Samples</a>
MAX3318CDBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MP318C	<a href="#">Samples</a>
MAX3318CPW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MP318C	<a href="#">Samples</a>
MAX3318CPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MP318C	<a href="#">Samples</a>
MAX3318IDB	ACTIVE	SSOP	DB	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP318I	<a href="#">Samples</a>
MAX3318IDBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP318I	<a href="#">Samples</a>
MAX3318IPW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP318I	<a href="#">Samples</a>
MAX3318IPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP318I	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

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**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MAX3318CDBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
MAX3318CPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
MAX3318IDBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
MAX3318IPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MAX3318CDBR	SSOP	DB	20	2000	367.0	367.0	38.0
MAX3318CPWR	TSSOP	PW	20	2000	367.0	367.0	38.0
MAX3318IDBR	SSOP	DB	20	2000	367.0	367.0	38.0
MAX3318IPWR	TSSOP	PW	20	2000	367.0	367.0	38.0

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



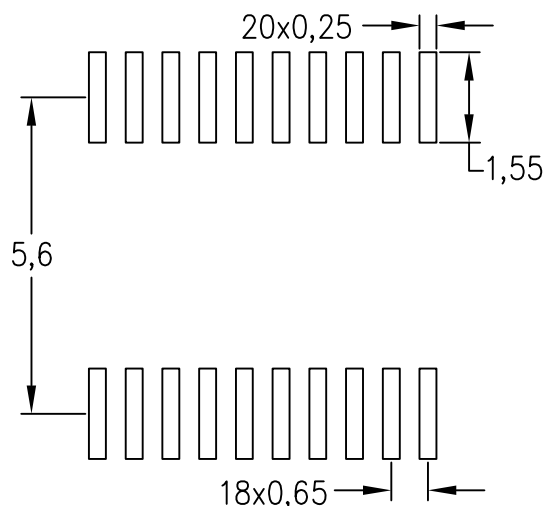
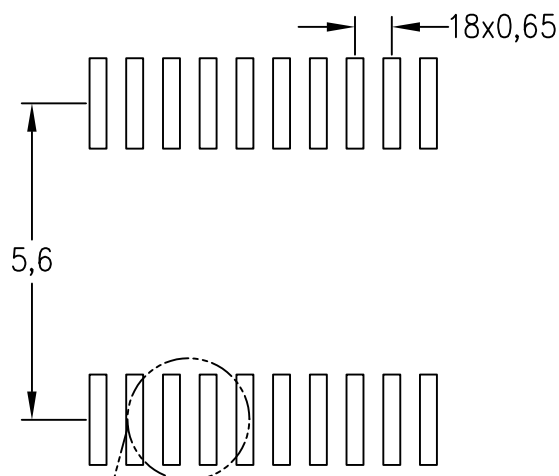
- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

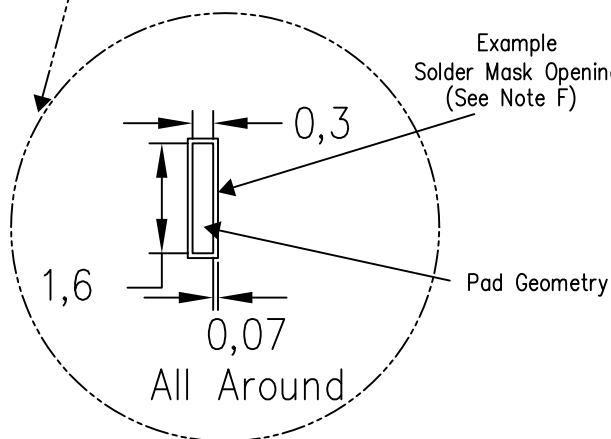
Example Board Layout

Based on a stencil thickness  
of .127mm (.005inch).



Example  
Non Soldermask Defined Pad

Example  
Solder Mask Opening  
(See Note F)



4211284-5/F 12/12

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

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